

# SPECIFICATION

- Supplier : Samsung electro-mechanics
- Product : Multi-layer Ceramic Capacitor

- Samsung P/N : **CL10C100DB8NNND**
- Description : **CAP, 10pF, 50V, ±0.5pF, COG, 0603**

## A. Samsung Part Number

CL   10   C   100   D   B   8   N   N   N   D  
 ①   ②   ③   ④   ⑤   ⑥   ⑦   ⑧   ⑨   ⑩   ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.6 ± 0.1 mm	W: 0.8 ± 0.1 mm
③ Dielectric	COG	⑧ Inner electrode	Ni
④ Capacitance	10 pF	Termination	Cu
⑤ Capacitance tolerance	±0.5 pF	Plating	Sn 100% (Pb Free)
⑥ Rated Voltage	50 V	⑨ Product	Normal
⑦ Thickness	0.8 ± 0.1 mm	⑩ Special	Reserved for future use
		⑪ Packaging	Cardboard Type, 13" reel

## B. Samsung Reliability Test and Judgement condition

	Performance	Test condition
<b>Capacitance</b>	Within specified tolerance	1MHz±10%      0.5~5Vrms
<b>Q</b>	600 min	
<b>Insulation Resistance</b>	10,000Mohm or 500Mohm·μF Whichever is Smaller	Rated Voltage      60~120 sec.
<b>Appearance</b>	No abnormal exterior appearance	Microscope (×10)
<b>Withstanding Voltage</b>	No dielectric breakdown or mechanical breakdown	300% of the rated voltage
<b>Temperature Characterisitcs</b>	COG (From -55℃ to 125℃, Capacitance change should be within ±30PPM/℃)	
<b>Adhesive Strength of Termination</b>	No peeling shall be occur on the terminal electrode	500g-F, for 10±1 sec.
<b>Bending Strength</b>	Capacitance change : within ±5% or ±0.5pF whichever is larger	Bending to the limit (1mm) with 1.0mm/sec.
<b>Solderability</b>	More than 75% of terminal surface is to be soldered newly	SnAg3.0Cu0.5 solder 245±5℃, 3±0.3sec. (preheating : 80~120℃ for 10~30sec.)
<b>Resistance to Soldering heat</b>	Capacitance change : within ±2.5% or ±0.25pF whichever is larger Tan δ, IR : initial spec.	Solder pot : 270±5℃, 10±1sec.

	<b>Performance</b>	<b>Test condition</b>
<b>Vibration Test</b>	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan $\delta$ , IR : initial spec.	Amplitude : 1.5mm From 10Hz to 55Hz (return : 1min.) 2hours $\times$ 3 direction (x, y, z)
<b>Moisture Resistance</b>	Capacitance change : within $\pm 7.5\%$ or $\pm 0.75\text{pF}$ whichever is larger Q : 133.33 min IR : 500Mohm or $25\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With rated voltage $40\pm 2^\circ\text{C}$ , 90~95%RH, 500+12/-0hrs
<b>High Temperature Resistance</b>	Capacitance change : within $\pm 3\%$ or $\pm 0.3\text{pF}$ whichever is larger Q : 300 min IR : 1000Mohm or $50\text{Mohm} \cdot \mu\text{F}$ Whichever is Smaller	With 200% of the rated voltage Max. operating temperature 1000+48/-0hrs
<b>Temperature Cycling</b>	Capacitance change : within $\pm 2.5\%$ or $\pm 0.25\text{pF}$ whichever is larger Tan $\delta$ , IR : initial spec.	1 cycle condition Min. operating temperature $\rightarrow 25^\circ\text{C}$ $\rightarrow$ Max. operating temperature $\rightarrow 25^\circ\text{C}$  5 cycle test

**C. Recommended Soldering method :**

Reflow ( Reflow Peak Temperature :  $260\pm 0/-5^\circ\text{C}$ , 10sec. Max )

\* For the more detail Specification, Please refer to the Samsung MLCC catalogue.